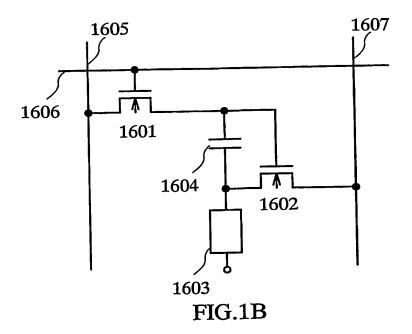
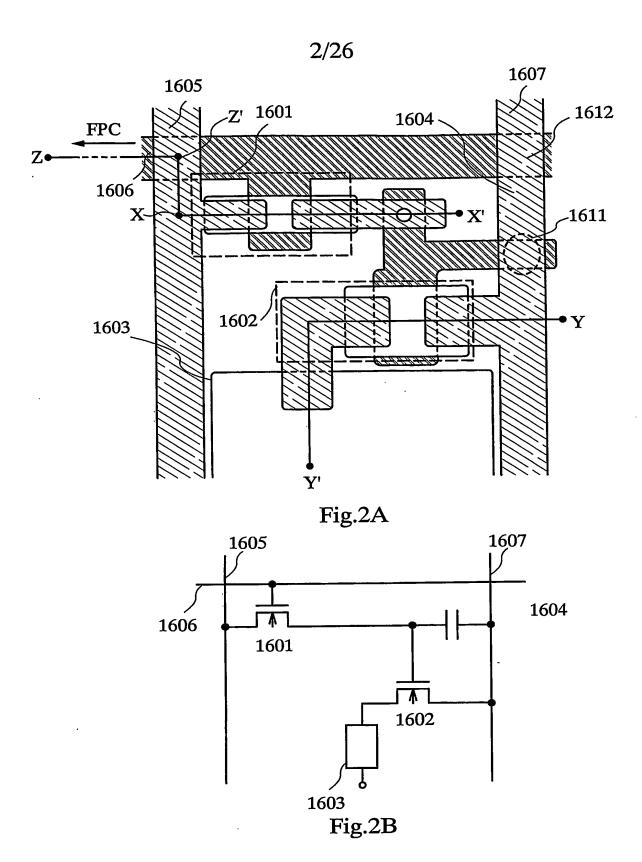


FIG.1A





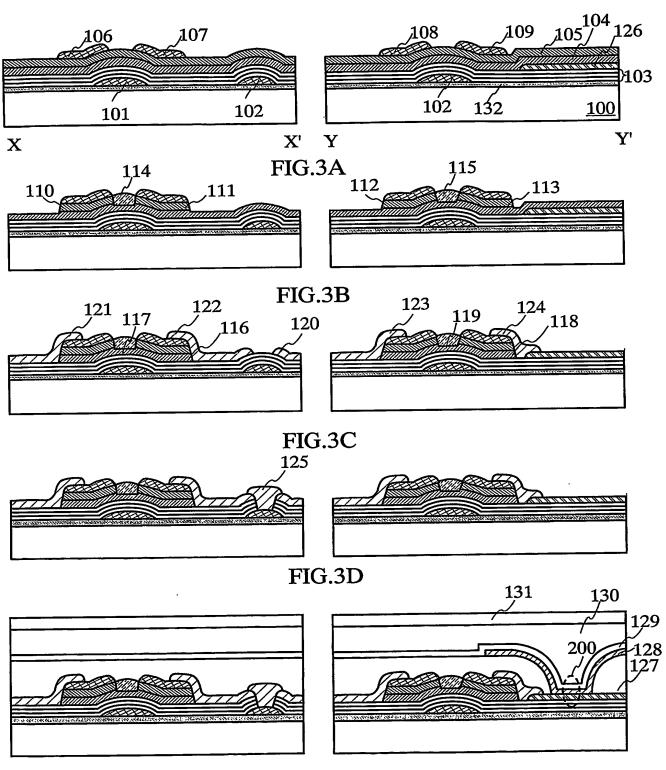
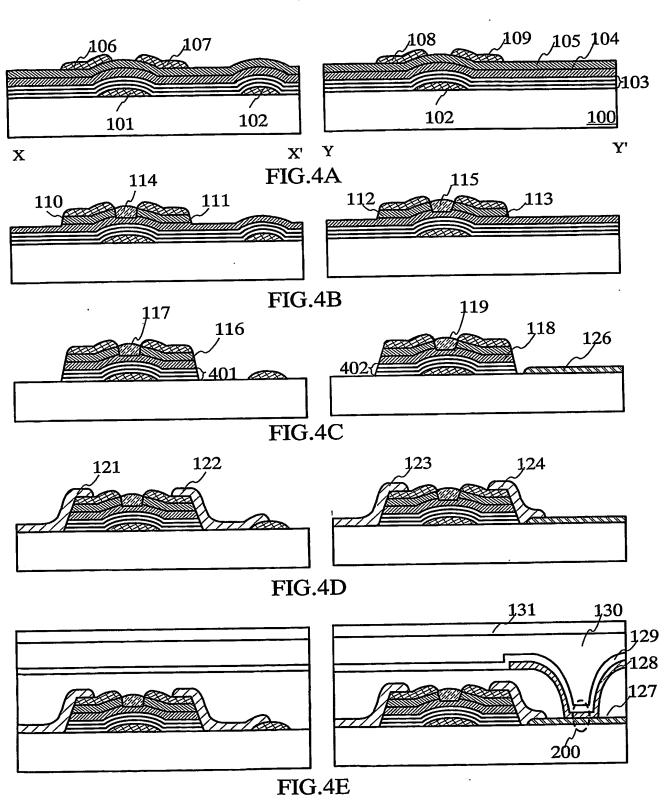
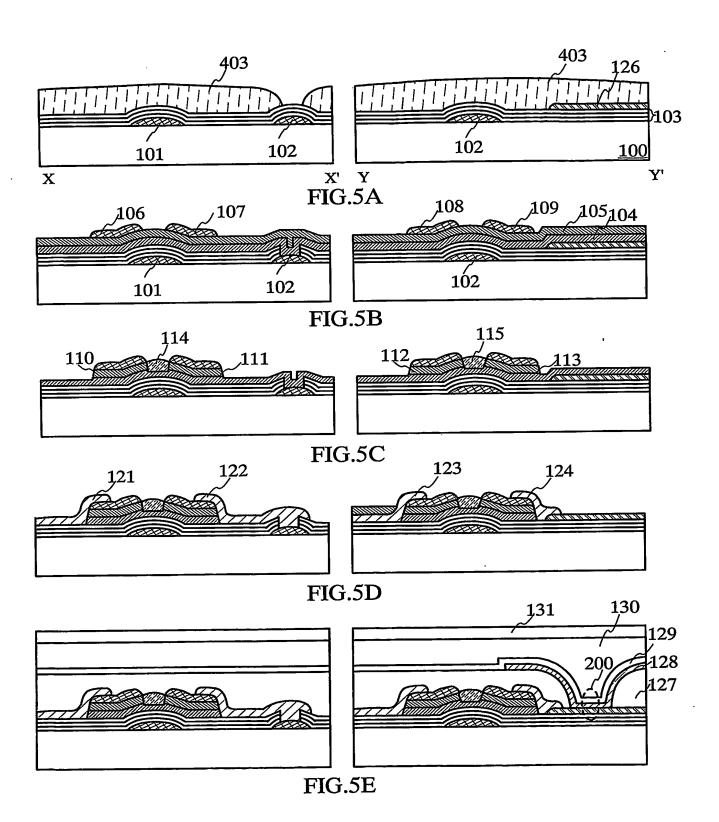


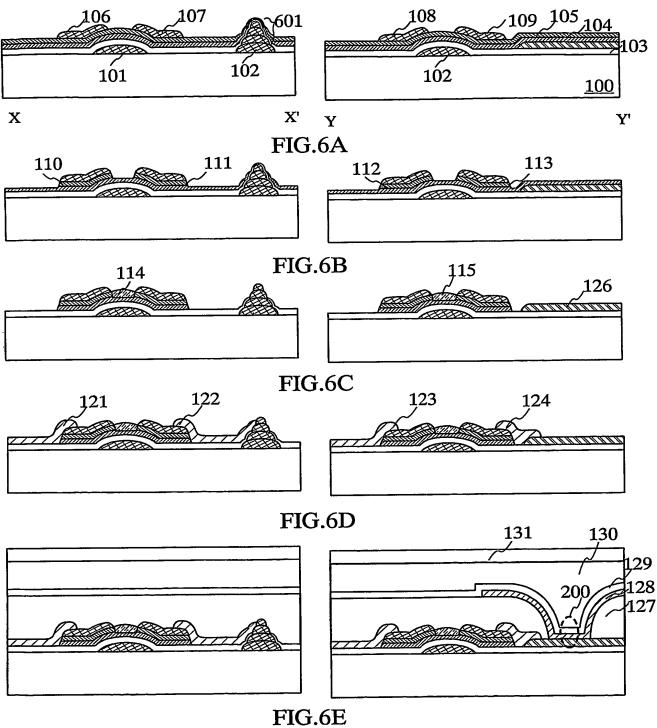
FIG.3E

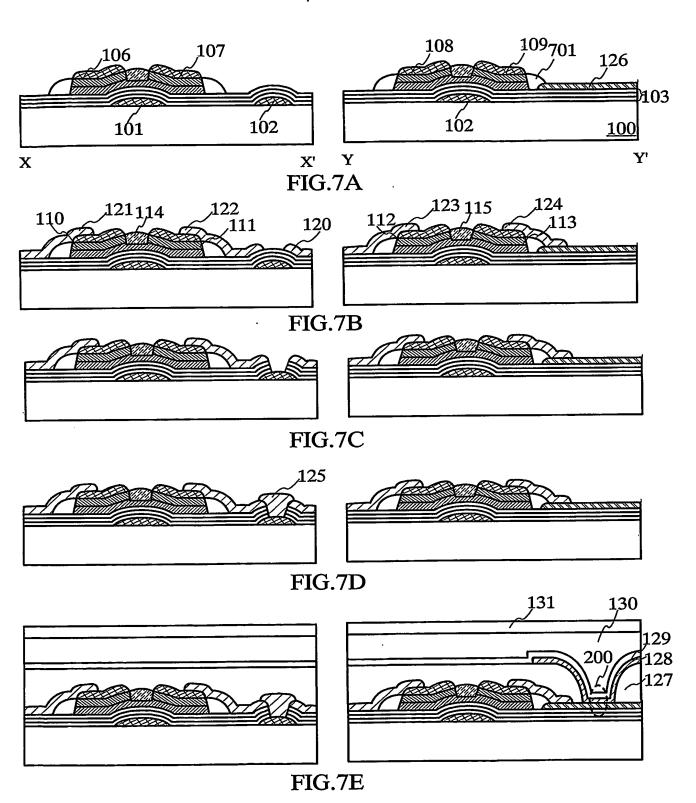


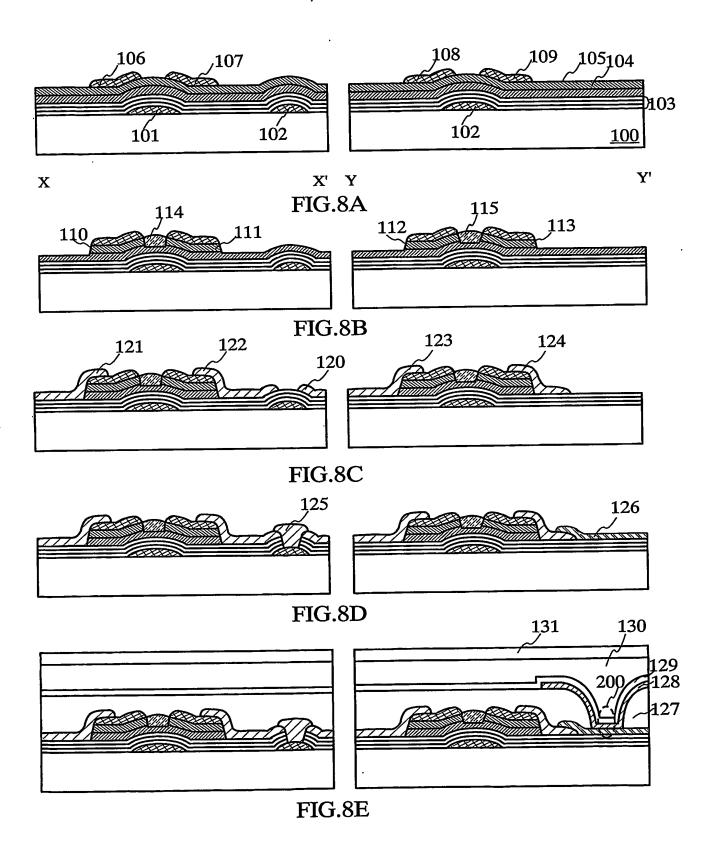
5/26



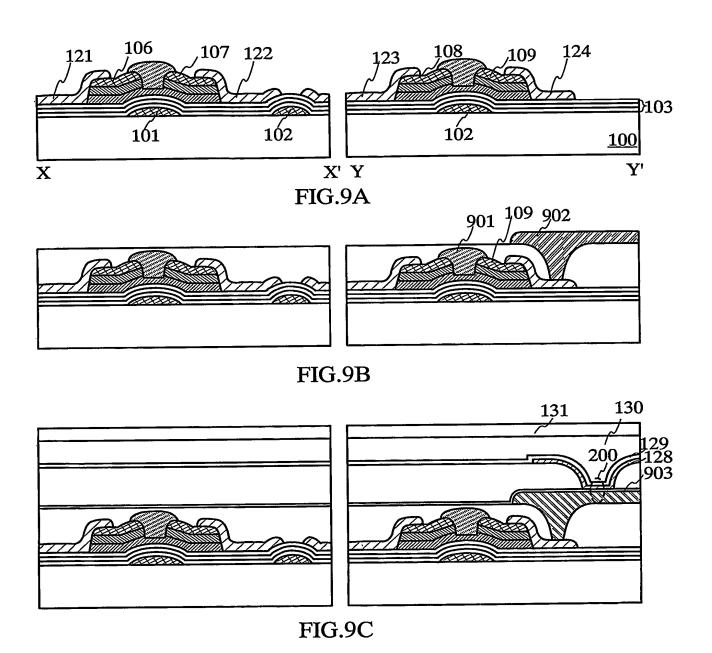
PCT/JP2004/016809 WO 2005/048223







9/26



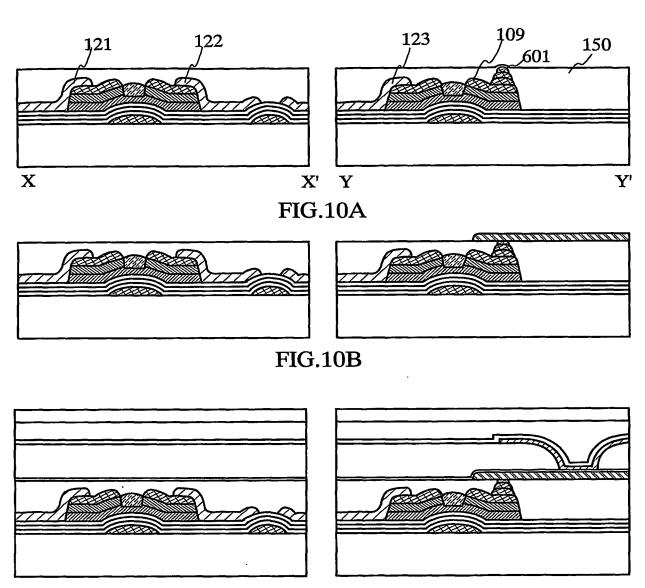


FIG.10C

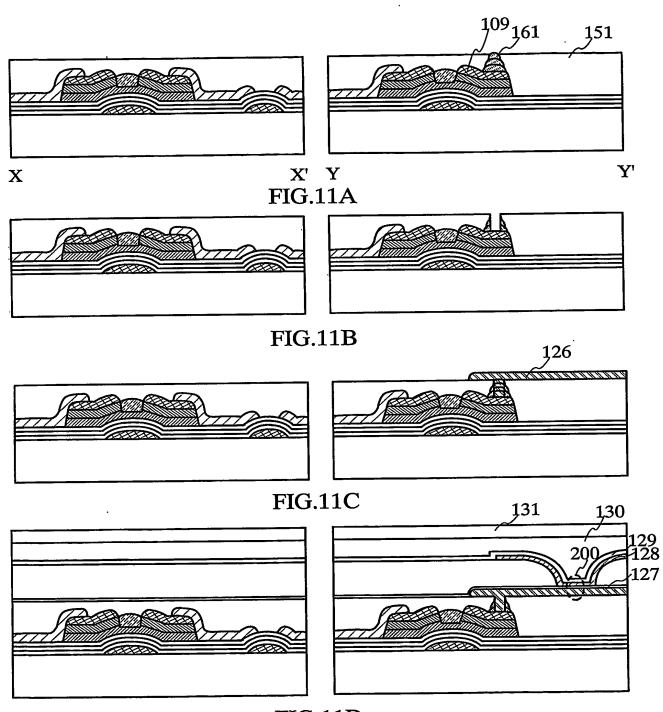


FIG.11D

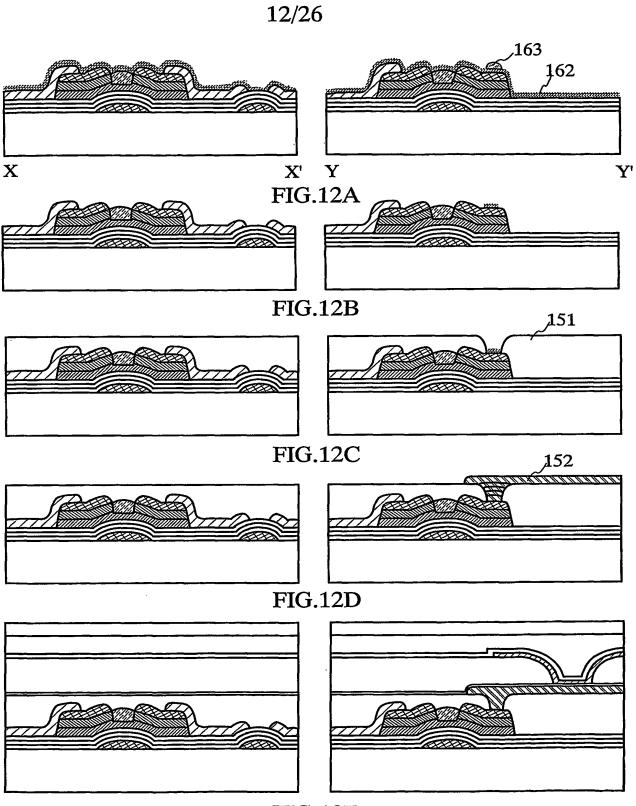
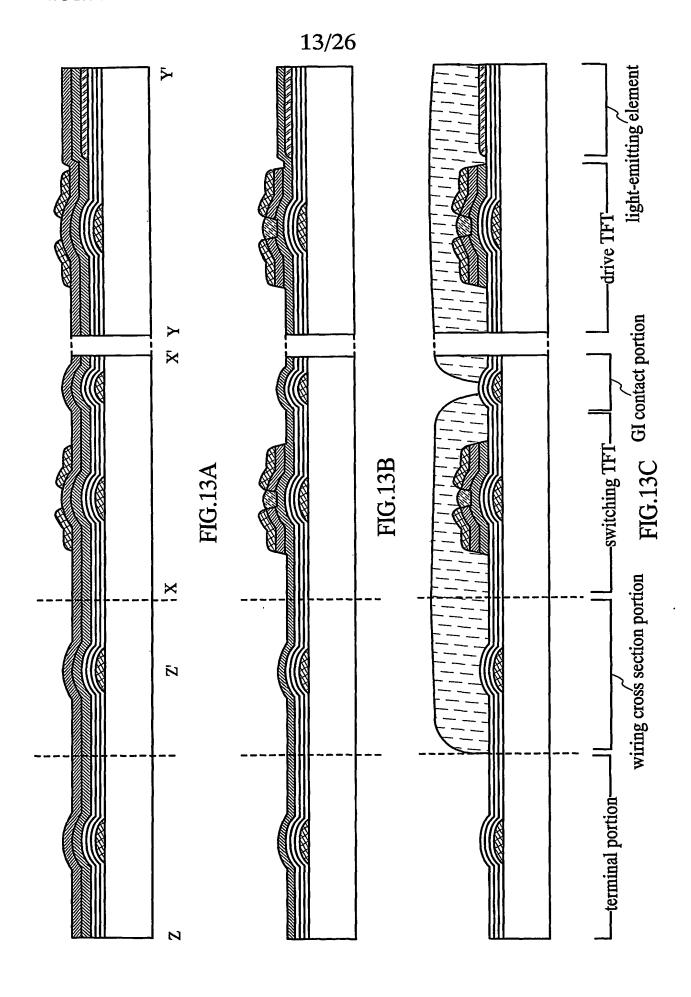
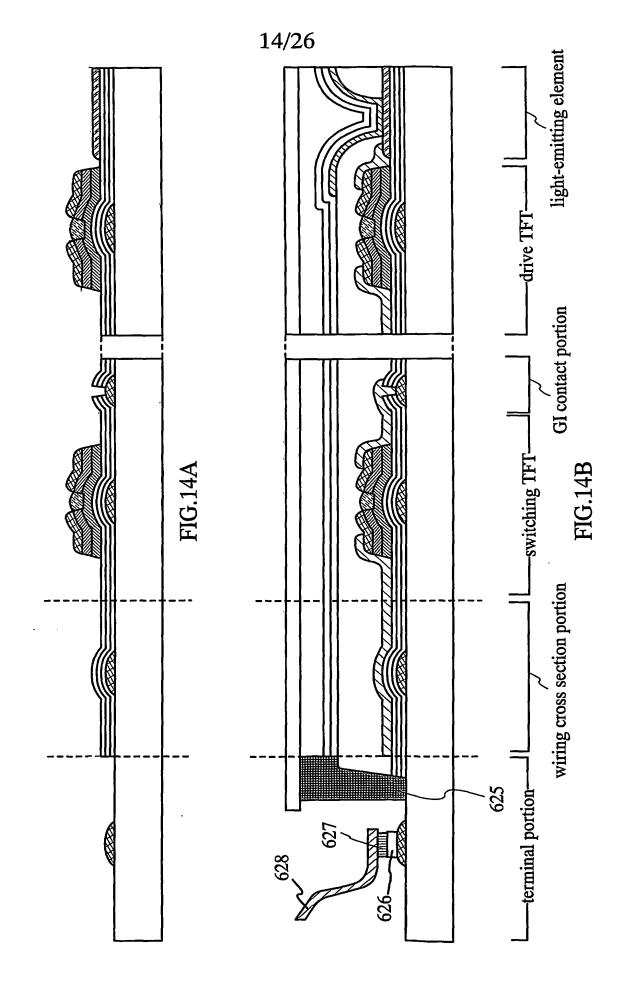
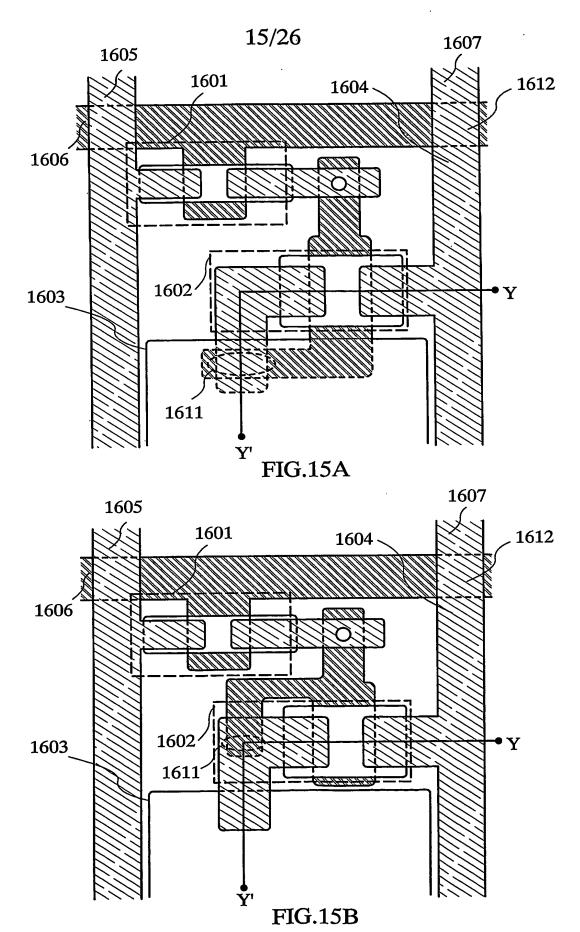


FIG.12E



PCT/JP2004/016809







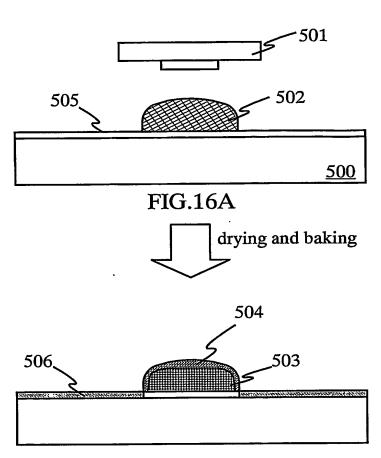


FIG.16B

baking in the atmosphere containing oxygen or oxygen plasma treatment

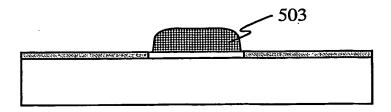


FIG.16C

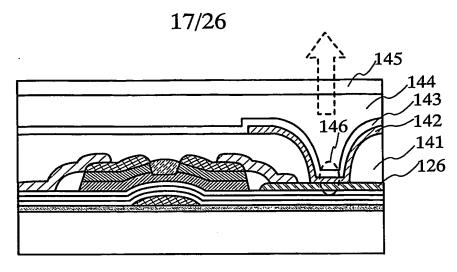
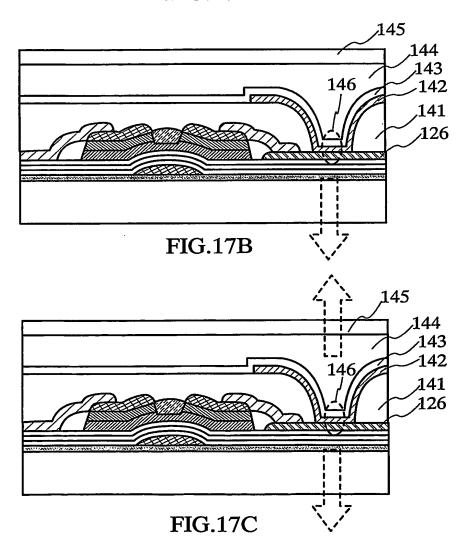


FIG.17A



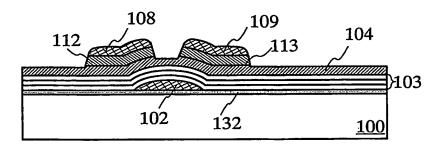


FIG.18A

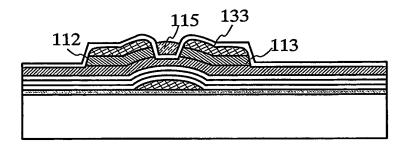


FIG.18B

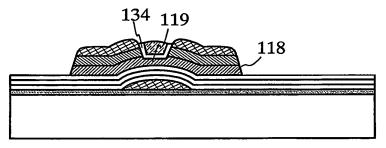


FIG.18C

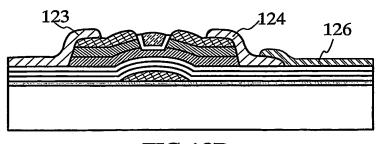
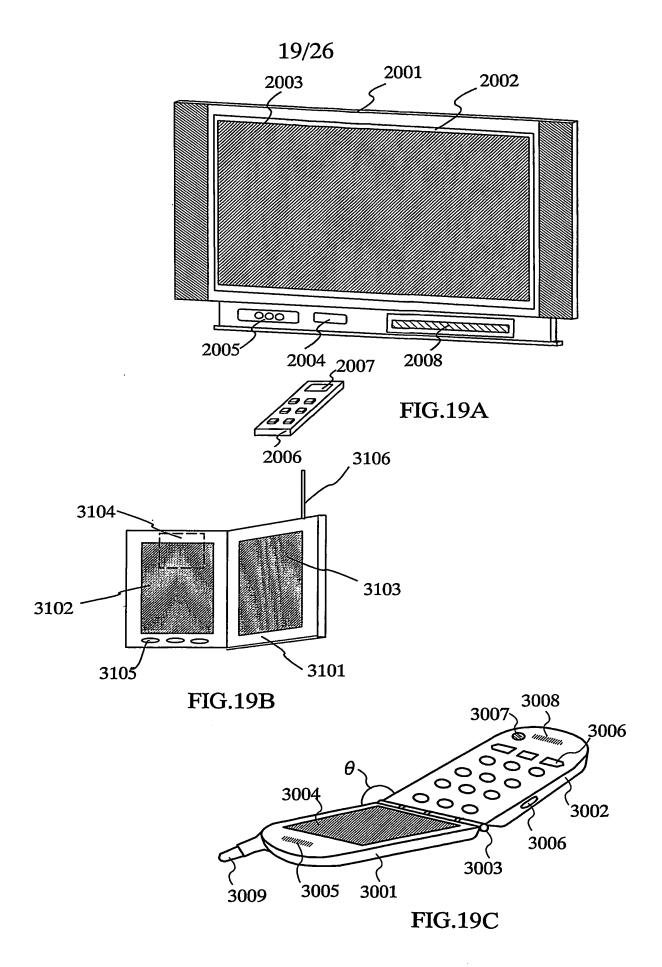
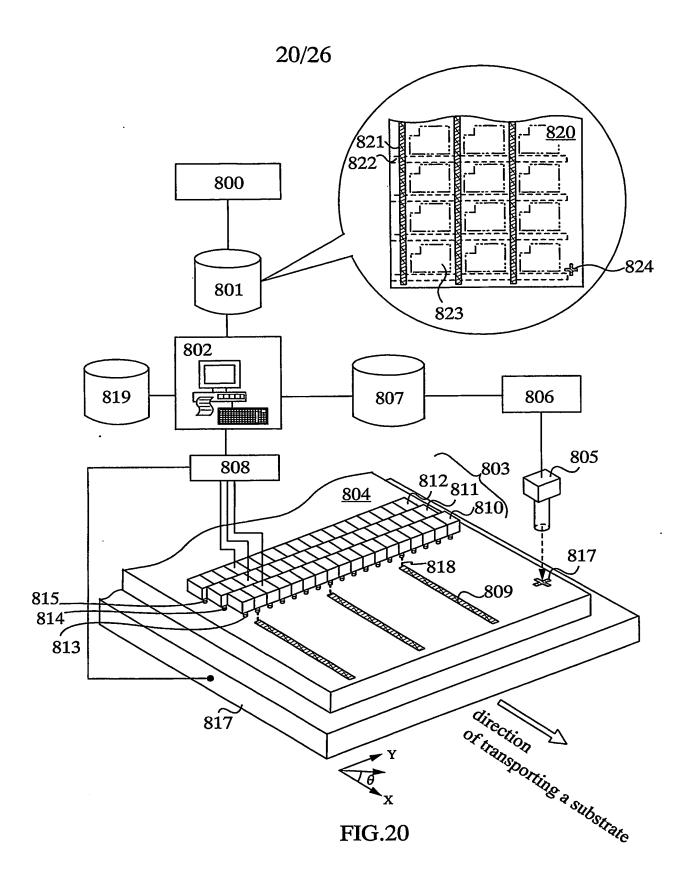
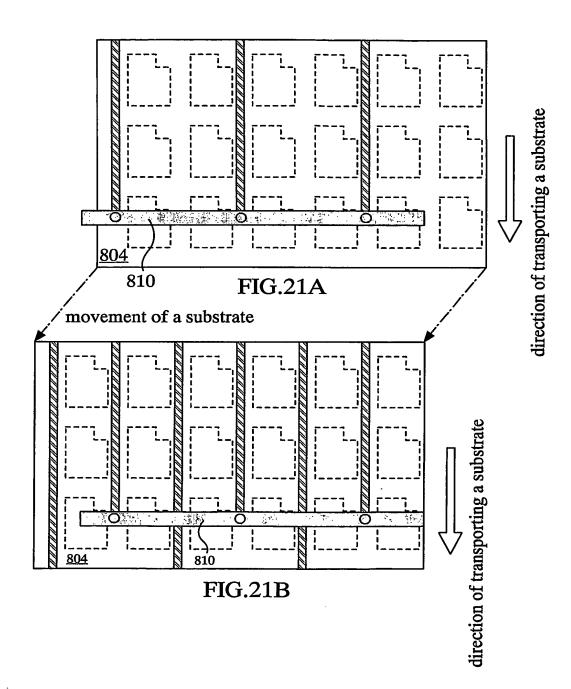


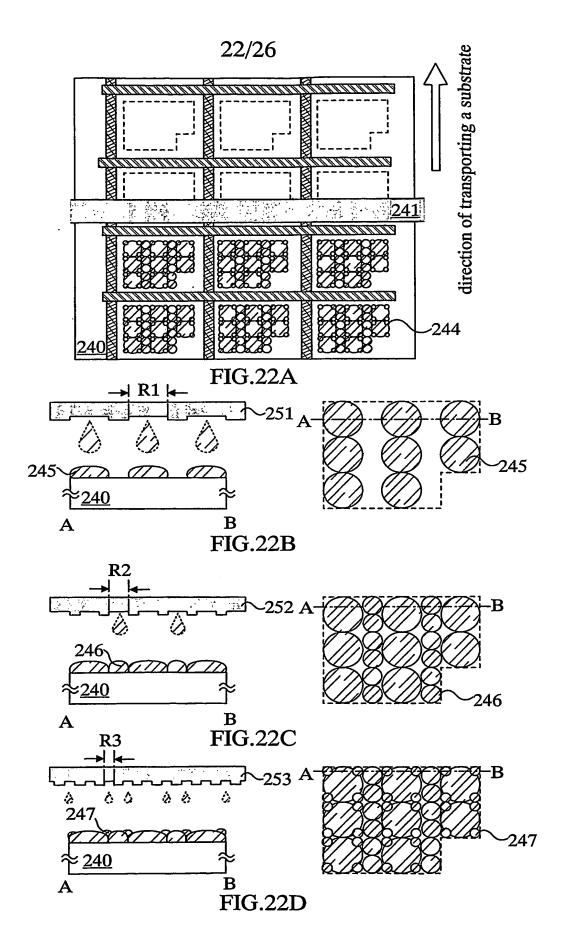
FIG.18D

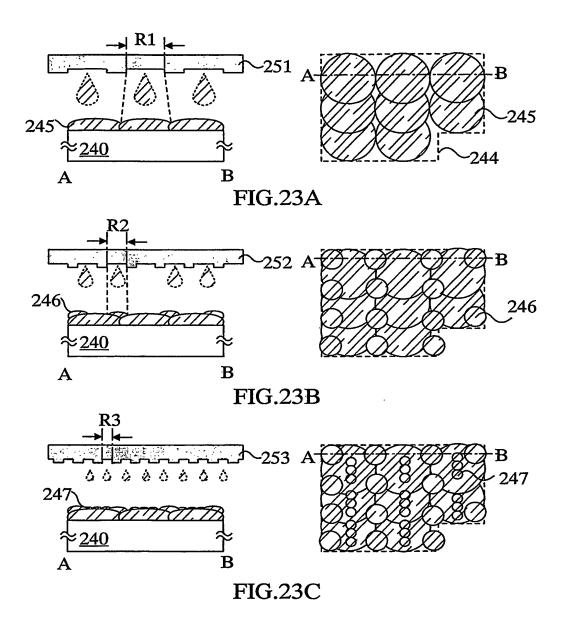


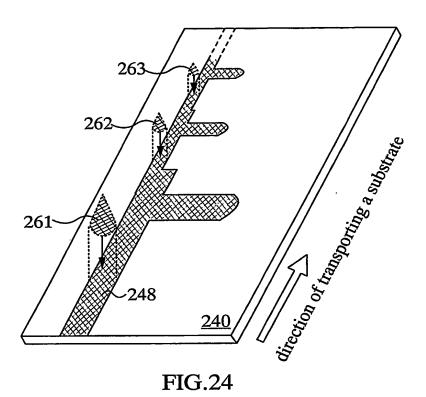


21/26

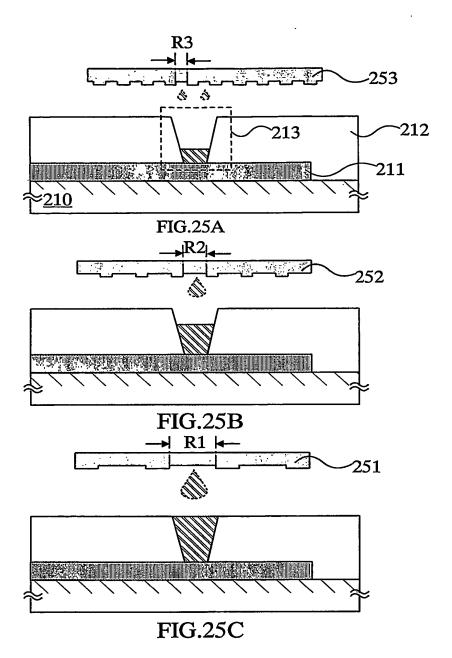








25/26



#### 26/26

#### **DESCRIPTION OF NUMERALS**

100:Substrate, 101-102:Gate electrode layer, 103:Gate insulating film,

104:Semiconductor film, 105:N-type semiconductor film, 106-109:Source or drain electrode, 110-113: Source or drain region, 114-115: Insulating film, 116: Island-like semiconductor film, 117:Channel region, 118:Island-like semiconductor film, 119: Channel region, 120: Wiring, 121-124: Source or drain wiring, 125: Conductor, 126:Pixel electrode, 127:Partition wall, 128:Organic compound layer, 129:Electron injecting electrode, 130:Passivation film, 131:Opposing substrate, 132:Titanium oxide film, 133:Silicon nitride film, 134:Insulating film, 141:Partition wall, 142:Organic compound layer, 143:Electron injecting electrode, 144:Passivation film, 145:Opposing substrate, 146:Light-emitting element, 150:Planarized film, 151:Planarized film, 161:Pillar insulator, 162:Liquid-shedding material, 152: Source or drain wiring, 163:Mask, 200:Light-emitting element, 210:Substrate, 211:Semiconductor or Conductor, 212:Insulator, 500:Glass substrate, 501:Nozzle, 502:Nano paste, 503:Conductor containing metal chains, 504:Film formed by organic ingredients, 626:Terminal electrode, 627:Anisotropic conductive film, 628:FPC, 652:Terminal portion, 654:Pixel TFT, 800: Circuit design tool, 801: Data of thin film pattern, 802: Computer, 805: Imaging means, 806:Image processing device, 807:Position information of alignment marker, 808:Controller, 816:XY0 stage, 817:Alignment marker, 819:Database, 2001:Housing, 2002:Display module, 2003:Main-screen, 2004:Modem, 2005:Receiver, 2006:Wireless remote control, 2007:Display portion, 2008:Sub-screen, 3001:Display panel, 3002:Operation panel, 3003:Connecting portion, 3004:Display portion, 3005:Voice output portion, 3006:Operation key, 3007:Power source switch, 3008:Voice input portion, 3009:Antenna, 3101:Main body, 3102:Display portion, 3103:Display portion, 3104:Memory medium, 3105:Operation switch, 3106:Antenna